

Title (en)

Platinum electroplating bath

Title (de)

Galvanisches Platinbad

Title (fr)

Bain de dépôt électrolytique de platine

Publication

**EP 0737760 B1 20000419 (DE)**

Application

**EP 96102799 A 19960224**

Priority

- DE 19514253 A 19950415
- DE 19547900 A 19951221

Abstract (en)

[origin: EP0737760A1] Platinum electroplating bath, esp. for depositing thick layers, contains 5-30 g/l Pt as an amine sulphamate complex and has pH less than 1, the novelty being that the electrolyte contains max. 5 g/l free amido-sulphuric acid, 20-400 g/l strong acid (pref. sulphuric acid, methane-sulphonic acid or perchloric acid) with pH less than 1 and pref. 0.01-0.2 g/l fluorine-contg. surfactant as wetting agent. Pref. the amine sulphamate complex is the product of reaction of 1 mol. Pt(II) diamine di:nitrite with 4-6 mol. amidosulphuric acid.

IPC 1-7

**C25D 3/50**; **C25D 3/56**

IPC 8 full level

**C25D 3/50** (2006.01); **C25D 3/52** (2006.01)

CPC (source: EP US)

**C25D 3/50** (2013.01 - EP US)

Cited by

WO2022129461A1; DE102020007789A1; DE102021107826A1; WO2022207539A1

Designated contracting state (EPC)

CH DE FR GB IT LI

DOCDB simple family (publication)

**EP 0737760 A1 19961016**; **EP 0737760 B1 20000419**; JP H08319595 A 19961203; US 5620583 A 19970415

DOCDB simple family (application)

**EP 96102799 A 19960224**; JP 8975096 A 19960411; US 62480696 A 19960327